

# International Symposium on Networks-on-Chip

# **Call for Papers**

15<sup>th</sup> IEEE/ACM International Symposium on Networks-on-Chip October 14-15, 2021, Virtual Conference

(Co-located with Embedded Systems Week 2021)

https://nocs2021.github.io/

The International Symposium on Networks-on-Chip (NOCS) is the premier event dedicated to interdisciplinary research on on-chip, package-scale, chip-to-chip, and datacenter rack-scale communication technology, architecture, design methods, applications and systems. NOCS brings together scientists and engineers working on NoC innovations and applications from inter-related research communities, including discrete optimization and algorithms, computer architecture, networking, circuits and systems, packaging, embedded systems, and design automation.

(New in 2021) Journal Special Issue: A selected number of accepted papers will be invited to be published in the ACM Journal on Emerging Technologies in Computing Systems, <u>Special Issue on Next-generation On-Chip and Off-Chip Communication Architectures for Edge</u>, Cloud and HPC.

Paper submission website: https://www.softconf.com/l/nocs2021/

More details at <a href="https://nocs2021.github.io/">https://nocs2021.github.io/</a>

# Topics of interest include, but are not limited to:

### **NoC Architecture and Implementation**

- Network architecture (topology, routing, arbitration)
- Timing, synchronous/asynchronous communication
- NoC reliability issues and solutions
- Security issues and solutions in NoC architectures
- Power/thermal issues at NoC un-core and system-level
- · Network interface issues and solutions
- Signaling and circuit design for NoC links and routers

# **Communication Analysis, Optimization, & Verification**

- NoC performance analysis and Quality of Service
- Modeling, simulation, and synthesis of NoC
- · Verification, debug and test of NoC
- NoC design and simulation methodologies and tools
- Benchmarks, experiences on NoC-based hardware
- Communication-efficient algorithms
- Communication workload characterization & evaluation

#### **Novel NoC Technologies**

- · Optical, wireless, CNT, and other emerging technologies
- NoC for 2.5D and 3D packages
- Package-specific NoC design
- Network coding and compression solutions
- Approximate computing for NoC and NoC-based systems

# **NoC for Intelligent Physical Systems**

- NoC design for Deep Learning
- Mapping of existing and emerging applications onto NoC
- NoC case studies, application-specific NoC design
- NoC for FPGA, structured ASIC, CMP and MPSoC
- · NoC designs for heterogeneous systems
- NoC for CPU-GPU and data-center-on-a-chip (DCoC)
- Scalable modeling of NoC
- Machine learning for NoC and NoC-based Systems

#### NoC at the Un-Core and System-level

- Design of memory subsystem (un-core) including memory controllers, caches, cache coherence protocols in NoC
- NoC for new memory/storage technologies
- NoC support for processing-in-memory
- OS support for NoC
- Programming models for NoCs
- Interactions between large-scale systems (datacenter, edge and fog computing) and NoC-based building blocks

### Inter/Intra-Chip and Rack-Scale Network

- Unified inter/intra-chip networks
- Hybrid chip-scale and datacenter rack-scale networks
- · All aspects of inter-chip and rack-scale network design

# **Organization Committee**

# **General Chairs**

Tushar Krishna (Georgia Tech) John Kim (KAIST)

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#### **Important Dates**

Abstract Registration: May 14th May 31st June 4th June 9th

Full-paper Submission: May 21st June 4th June 9th

Notification of Acceptance: July 23rd